

ABSTRACT

An integrated circuit package assembly includes an integrated circuit, and a plurality of layers sealably connectable to each other to form a package having a cavity sized and shaped to receive the integrated circuit. Each layer is formed of a respective material. Each respective material is suitable for use as a printed circuit board substrate. At least one of the plurality of layers is a substrate having contacts that are connectable to electrical contacts of the integrated circuit. A bottom one of the layers has a plurality of ball attach pads, electrically connected to the contacts of the substrate.

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